

IN THE CLAIMS

Please replace claim 1 with the following:

1. (amended) An arrangement for cooling an electronic assembly, the arrangement comprising:

a circuit board having a first surface, a second surface, and at least a first heat-generating element secured to the first surface, the circuit board further comprising at least one aperture extending between the first surface and the second surface;

an enclosure member secured to said circuit board so as to form a fluid tight barrier of a compartment defined at least in part by said enclosure member, said compartment including a first subcompartment defined at least in part by said first surface and said enclosure member and a second subcompartment defined at least in part by said second surface and said enclosure member; and

at least one electromechanical actuator secured within the fluid type barrier, at least a portion of the at least one electromechanical actuator disposed over the at least one aperture, the electromechanical actuator operable to generate a flow movement in the direction of the at least one aperture when liquid is disposed in the fluid tight barrier.